

IN THE CLAIMS:

## Claim 1 (currently amended)

1. A method of packaging a PVA sponge (for use in scrubbing semiconductor wafers, said method comprising:

- (a) placing said sponge in a [container] flexible plastic bag;
- (b) said sponge containing a quantity of de-ionized water with around 0.05% to substantially less than 1% by volume of hydrogen peroxide; and
- (c) sealing said [container] bag.

## Claim 2 (withdrawn)

## Claim 3 (previously amended)

3. A method as in Claim 1 in which said quantity of de-ionized water with hydrogen peroxide is between an amount sufficient to wet said sponge and an amount necessary to saturate said sponge.

## Claim 4 (previously amended)

4. A method as in Claim 1 in which the volume of hydrogen peroxide is around 0.1%.

## Claim 5 (currently amended)

A method of packaging a [cleaning article] PVA sponge <sup>PVA sponge brush</sup> brush, said method comprising placing said cleaning article in a [container] plastic bag, said [cleaning article] sponge brush

containing a quantity of de-ionized water, said water containing hydrogen peroxide in an amount effective to kill and retard the ~~sponge brush~~ growth of bacteria in said ~~cleaning article~~ but less than an amount sufficient to develop significant quantities of metallic ions in said ~~container~~, and sealing said ~~container~~, in which said amount of hydrogen peroxide is about 0.05% to substantially less than 1% by volume.

Claim 6 (withdrawn)

Claim 7 (withdrawn)

Claim 8 (withdrawn)

Claim 9 (currently amended)

A packaged [cleaning article] PVA sponge for use in clean rooms, said cleaning article having particulate, metal ion and anionic counts at or below the values specified for a clean room, said package comprising a sealed [container] flexible plastic bag, said [cleaning article] sponge being positioned in said [container] bag, and containing a quantity of de-ionized water, said de-ionized water containing hydrogen peroxide in a concentration effective to kill and retard the growth of bacteria in said [cleaning article] sponge, said amount being low enough to substantially ensure decomposition of said hydrogen peroxide in a relatively short period of time after the

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container is sealed and being between 0.05% and substantially less than 1% by volume.

Claim 10 (withdrawn)

Claim 11 (withdrawn)

Claim 12 (previously amended)

*LAB PVA SPONGE*  
12. A ~~cleaning~~ article as in Claim 9 in which said ~~cleaning~~ article is a ~~PVA~~ sponge for scrubbing semiconductor wafer surfaces, and said concentration of hydrogen peroxide is around 0.1 percent by volume.

Claim 13 (withdrawn)

Claim 14 (withdrawn)